

Second Call for Papers

13th US-Japan Conference on Composite Materials

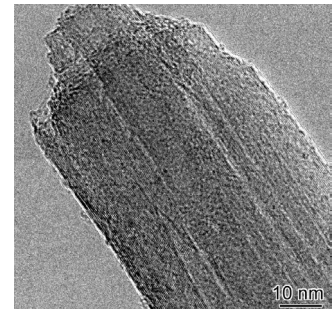
June 6-7, 2008, Surugadai Campus, Nihon University, Tokyo, Japan

Sponsored by Japan Society for Composite Materials (JSCM)

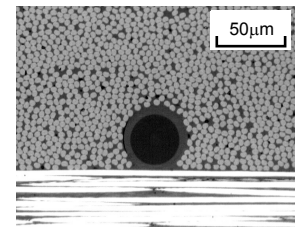
Co-sponsored by American Society for Composites (ASC)

The collaboration between US and Japan in composite materials and structures has been very successful both academically as well as commercially, including recent Boeing-Japan partnership in the 787 development. Following a long tradition of US-Japan Conference, we are now emphasizing the present cutting edge technology topics to promote more lively discussion. The following *Special Sessions* are being planned:

- (1) Nanocomposites: Modeling and Reality
- (2) Multiscale Modeling
- (3) Multifunctional Composites
- (4) Increased Fidelity in Composites Analysis and Design
- (5) Composite Affordability and Certification
- (6) Composite Durability
- (7) Structural Health Monitoring and Nondestructive Evaluation



Carbon nanotube



Embedded optical fiber in composites

General sessions are also planned on the following topics of interest:

Materials: Resin, Reinforcements and Preform, Textile Composites, Interface and Interphase, Metal Matrix Composites, Ceramic Matrix Composites, Thermoplastic Matrix Composites, Bio-composites

Manufacturing: RTM, VaRTM, Filament Winding, Prepreg, Pultrusion, Compression Molding, Curing Studies, Forming

Property: Test Methods, Impact, Energy Absorption, Fatigue, Creep, Vibration & Damping

Mechanics: Micromechanics, Modeling, Damage Mechanics, Design and Optimization, Joints

Application: Aircraft, Space, Automobile, Marine, Sports, Infrastructure, Energy, Electronics

Life Cycle Assessment: Environmental Impact, Life Cycle Costing, Recycling

Conference Chairpersons

Prof. Nobuo Takeda, University of Tokyo, Tokyo, Japan

Prof. R. Byron Pipes, Purdue University, West Lafayette, IN, USA

Abstract Submission

Abstracts (500-800 words) should be submitted electronically at usjapan2008@smart.k.u-tokyo.ac.jp.

Important Dates

- **January 10, 2008** (Extended) Deadline for abstract submission
- **February 1, 2008** (Extended) Notification of abstract acceptance
- **March 10, 2008** (Extended) Deadline for manuscript submission

Registration Fees

Regular Fees: 30,000 Japanese Yen

Student Fees: 20,000 Japanese Yen

The registration fee covers the symposium participation, a program, a CD-ROM Proceeding, coffee breaks, and a banquet ticket (on June 6 evening). Payment of the registration fee can be made by Credit Card. Please see our website for the details.

Location

The conference is held at Surugadai campus of College of Science and Technology, Nihon University. (http://www.cst.nihon-u.ac.jp/english/life/c_map.html) The conference venue is just three minutes' walk from JR Ochanomizu station, which is close to JR Tokyo station. List of recommended accommodation will be provided in the website.

List of travel agents

<http://travel.rakuten.co.jp/en/>

<http://www.nta.co.jp/english/>

<http://www.knt.co.jp/kokusai/index.html>

Conference website www.smart.k.u-tokyo.ac.jp/usjapan2008

Contact e-mail address: takeda@smart.k.u-tokyo.ac.jp (Prof. Nobuo Takeda)

(日本複合材料学会会員の皆様)

申し込み締め切りは、1月10日とさせていただきますが、発表をご希望の方は是非、武田 (takeda@smart.k.u-tokyo.ac.jp) までお問い合わせください。日米の発表論文のバランスを考慮し、1月末日までは追加論文も受け付ける予定です。

登録料は予め、郵便振込みしていただく(詳細は website 参照) 予定です。なお、2008年6月5日(木)に東京大学山上会館にて開催される、日本複合材料学会2008年度研究発表講演会にもご出席の方が、本会議にもご参加いただき、かつ、4月30日までに振込みを行っていただいた場合には、登録料を割り引かせていただき、Regular Fees: 27,000 Japanese Yen、Student Fees: 18,000 Japanese Yen とさせていただきます。